IDT

Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **I0406-01**	DATE: June 21, 2004	MEANS OF DISTINGUISHING CHANGED DEVICES:
Product Affected: IDT79RC32H434		☐ Product Mark
		☐ Back Mark
		■ Date Code ZB0426 and later
Date Effective: June 21, 2004		☐ Other

Contact:	Bimla Paul		
Title:	Product Assurance Manager	Attachment::	■ Yes ☐ No
Phone #:	408-654-6419		
Fax #:	408-492-8362	Samples:	Available upon request
E-mail:	bimla.paul@idt.com		

DESCRIPTION AND PURPOSE OF CHANGE:

☐ Die Technology
☐ Wafer Fabrication Process
☐ Assembly Process
☐ Equipment   Data Sheet Change to add I2C bus interface functionality to the device.
☐ Material   This adds, identifies and describes two pins (SCL and SDA) functionality.
☐ Testing
☐ Manufacturing Site One timing parameter change to align with Industry guidelines.
■ Data Sheet
☐ Other

There is no change in die technology/process

RELIABILITY/QUALIFICATION SUMMARY: N/A Datasheet change only. There is no change to die technology/process.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail
to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice
it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory
on the earlier version has been depleted.

Customer: _____   ☐ *Approval for shipments prior to effective date.*

Name/Date: _____   E-Mail Address: _____

Title: _____   Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____   DATE: _____

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ATTACHMENT - PCN #: I0406-01

PCN Type: Data Sheet Revision

Data Sheet Change

Detail of Change   **Add I2C references on the following pages**

1. Page 1, Block Diagram .

2. Page 2, I2C Bus Description.

3. Page 3, I2C Interface Description.

4. Page 8, I2C Bus Interface Signal Name/Description.

5. Page 10, I2C Bus Interface Pin Function/Description.

6. Page 14, Logic Diagram.

7. Page 29, 30 I2C AC Timing Characteristics and Waveform.

8. Page 50, Alphabetical Signal list, Adding SCL and SDA (I2C signal category) reference

Make the following change to page 25:   Change affects all speed Grades

Signal	Symbol	From	To
MIIRXCLK	Thigh_9d	18 nsec Min, 22 nsec Max	14 nsec Min, 26 nsec Max
MIITXCLK	Tlow_9d		

There is no change in die technology/process.